



Low-Resistance Molded Inductor 1.5µH

APPLICATIONS



- Battery-powered devices
- Embedded computing
- High-current SMPS
- High-frequency SMPS
- POL converters
- FPGA

FEATURES

- Size 5.5mmx5.3mmx2.9mm
- Low DCR
- Low AC Losses
- Low Audible Noise
- Molded Construction
- Soft Saturation
- Stable Over High Temperatures
- Max Operating Temp +155°C
- RoHS/REACH-Compliant, Halogen-Free

ELECTRICAL CHARACTERISTICS					
Parameter			Value	Unit	
Inductance (1)	L	±20%	1.5	μH	
Resistance	R _{DC}	typ	9.7	mΩ	
Resistance MAX	RDC MAX	max	11.3	mΩ	
Rated Current (2)	I _R	typ	9.0	Α	
Saturation Current _{25°C} (3)	ISAT 25°C	typ	12.5	Α	
Saturation Current 100°C (4)	ISAT 100°C	typ	12.5	Α	
Resonance Frequency	fr	typ	36	MHz	

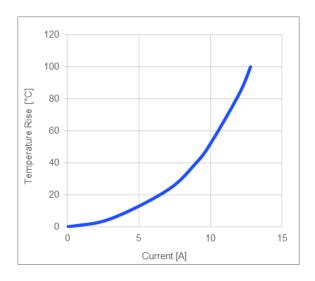
GENERAL SPECIFICATIONS		
(1) Inductance	Measured at 100kHz, 100mA	
(2) Rated Current	Rated current will cause the coil temperature rise ΔT of 40K I_R measured with the inductor soldered in a single-layer PCB. Copper layer thickness 35 μ m Cu / PCB size 30x50mm. Temperature behavior dependent on circuit design, PCB layout, proximity to other components, and trace dimensions and thickness.	
(3) Saturation Current 25°C	Saturation current will cause L to drop from 30% at 25°C ambient temperature	
(4) Saturation Current 100°C	Saturation current will cause L to drop from 30% at 100°C ambient temperature	
Temperature Test Condition	Electrical specifications measured at 25°C, 35% RH if not given differently	
Operating Condition	Operating temperature: -40°C to +155°C (including temp rise)	
	Should not exceed +155°C under worst-case operation conditions	
Storage Condition	Tape and Reel packaging: -10°C to +40°C	
	Humidity: <50% RH	

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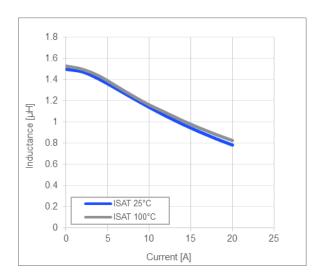


TYPICAL PERFORMANCE CURVES

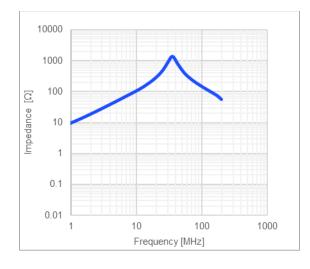
Temperature Rise vs. Current



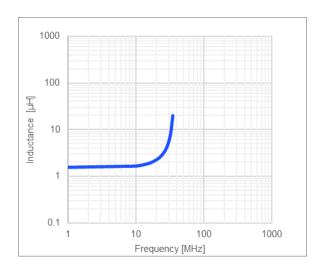
Inductance vs. Current



Impedance vs. Frequency

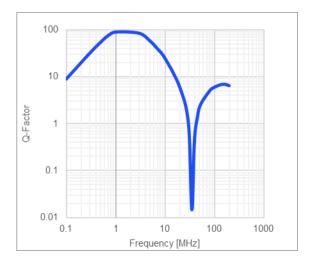


Inductance vs. Frequency

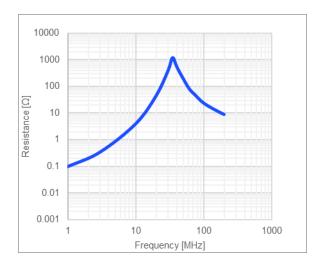




Quality Factor vs. Frequency

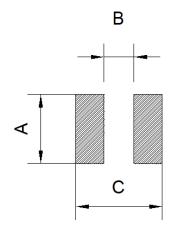


AC Resistance vs. Frequency





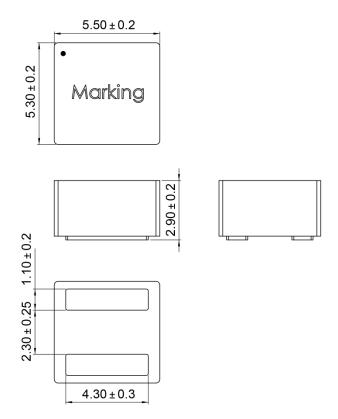
LAND PATTERN		
Dimensions		
Α	4.70 ref.	
В	2.0 ref.	
С	4.50 ref.	
	(unit in mm)	



PRODUCT PACKAGE AND DIMENSIONS

Dimensions

(unit in mm)



TOP MARKING Marking Start of Winding · (dot) Inductance Code 1R5 MPS Code MPS



ORDERING INFORMATION					
Part Number	<u>L</u> (1)	RDC	I _R ⁽²⁾	ISAT 25°C (3)	ISAT 100°C (4)
	typ (µH)	typ (mΩ)	typ (A)	typ (A)	typ (A)
MPL-AL5030-R47	0.47	3.78	13.6	26.5	26.5
MPL-AL5030-R56	0.56	3.92	13.2	22	22
MPL-AL5030-R82	0.82	5.0	12.8	18	18
MPL-AL5030-1R0	1.0	6.5	11.2	16	16
MPL-AL5030-1R2	1.2	8.0	10.0	14	14
MPL-AL5030-1R5	1.5	9.7	9.0	12.5	12.5
MPL-AL5030-1R8	1.8	10.5	8.8	12	12
MPL-AL5030-2R2	2.2	12.3	8.2	11	11
MPL-AL5030-3R3	3.3	21	6.0	10	10
MPL-AL5030-4R7	4.7	33	5.3	8	8

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Storage Condition	Tape and Reel packaging: -10°C to +40°C	
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